

主要参数 MAIN CHARACTERISTICS

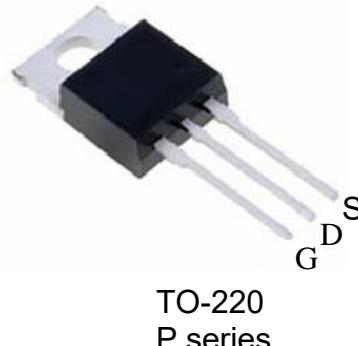
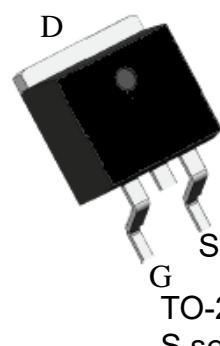
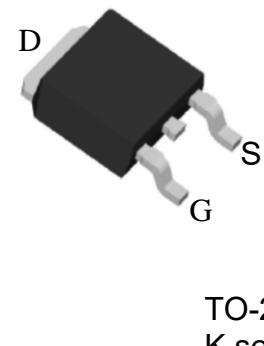
ID	80A
VDSS	75V
Rdson-typ (@Vgs=10V)	7mΩ
Qg-typ	45nC

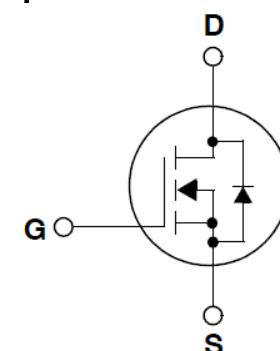
用途 APPLICATIONS

电池管理系统	BMS
电机控制和驱动	Motor control and drive
不间断电源	UPS

产品特性 FEATURES

低栅极电荷	Low gate charge
低 Crss (典型值 142pF)	Low Crss (typical 142pF)
开关速度快	Fast switching
100% 经过雪崩测试	100% avalanche tested
高抗 dv/dt 能力	Improved dv/dt capability
RoHS 产品	RoHS product

封装形式 Package

 TO-220
P series

 TO-263
S series

 TO-252
K series

等效电路 Equivalent Circuit

绝对最大额定值 ABSOLUTE RATINGS (Tc=25°C)

项目 Parameter	符号 Symbol	数值 Value			单位 Unit
		80N75			
最高漏极—源极直流电压 <i>Drain-Source Voltage</i>	V _{DS}	75			V
连续漏极电流* <i>Drain Current -continuous *</i>	I _D (T _c =25°C)	80			A
	I _D (T _c =100°C)	63			A
最大脉冲漏极电流 (注 1) <i>Drain Current – pulse (note 1)</i>	I _{DM}	320			A
最高栅源电压 <i>Gate-Source Voltage</i>	V _{Gs}	±20			V
单脉冲雪崩能量 (注 2) <i>Single Pulsed Avalanche Energy (note 2)</i>	E _{AS}	50			mJ
雪崩电流 (注 1) <i>Avalanche Current (note 1)</i>	I _{AR}	10			A
重复雪崩能量 (注 1) <i>Repetitive Avalanche Current (note 1)</i>	E _{AR}	4			mJ
二极管反向恢复最大电压变化速率 (注 3) <i>Peak Diode Recovery dv/dt (note 3)</i>	dv/dt	5.0			V/ns
耗散功率 <i>Power Dissipation</i>	P _D (T _C =25°C)	195	195	88	W
	-Derate above 25°C	0.6	0.6	0.7	W/°C
最高结温及存储温度 <i>Operating and Storage Temperature Range</i>	T _J , T _{STG}	-55~+150			°C
引线最高焊接温度 <i>Maximum Lead Temperature for Soldering Purposes</i>	T _L	300			°C

*漏极电流由最高结温限制

*Drain current limited by maximum junction temperature

电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units	
关态特性 Off -Characteristics							
漏—源击穿电压 Drain-Source Voltage	BVDSS	ID=250μA, VGS=0V	75	-	-	V	
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	ΔBVDSS/Δ TJ	ID=250μA, referenced to 25°C	-	0.06	-	V/°C	
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	IDSS	VDS=60V, VGS=0V, Tc=25°C	-	-	1	μA	
		VDS=48V, Tc=125°C	-	-	100	μA	
栅极体漏电流 Gate-body leakage current	IGSS (F/R)	VDS=0V, VGS =±20V	-	-	±100	nA	
通态特性 On-Characteristics							
阈值电压 Gate Threshold Voltage	VGS(th)	VDS = VGS , ID=250μA	1.3	1.6	2.3	V	
静态导通电阻 Static Drain-Source On-Resistance	RDS(ON)	VGS =10V , ID=30A	-	6.4	9	mΩ	
		VGS =4.5V , ID=25A		9.5	11		
正向跨导 Forward Transconductance	gfs	VDS = 5V, ID=30A (note 4)	-	65	-	S	
动态特性 Dynamic Characteristics							
栅电阻 Gate Resistance	Rg	f=1.0MHz, VDS OPEN	-	1.1	-	Ω	
输入电容 Input capacitance	Ciss	VDS=30V, VGS =0V, f=1.0MHz	-	1940	-	pF	
输出电容 Output capacitance	Coss		-	197	-		
反向传输电容 Reverse transfer capacitance	Crss		-	142	-		
开关特性 Switching Characteristics							
延迟时间 Turn-On delay time	td(on)	VDD=30V, ID=30A, RG=2.7Ω VGS =10V (note 4, 5)	-	10	-	ns	
上升时间 Turn-On rise time	tr		-	50	-	ns	
延迟时间 Turn-Off delay time	td(off)		-	30	-	ns	
下降时间 Turn-Off Fall time	tf		-	72	-	ns	
栅极电荷总量 Total Gate Charge	Qg	VDS =30V , ID=30A , VGS =10V (note 4, 5)	-	45	-	nC	
栅—源电荷 Gate-Source charge	Qgs		-	9	-	nC	
栅—漏电荷 Gate-Drain charge	Qgd		-	13	-	nC	
漏—源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings							
正向最大连续电流 Maximum Continuous Drain -Source Diode Forward Current	Is		-	-	80	A	
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current	ISM		-	-	320	A	
正向压降 Drain-Source Diode Forward Voltage	VSD	VGS=0V, Is=30A	-	0.8	1.3	V	
反向恢复时间 Reverse recovery time	trr	VGS=0V, Is=30A ,dI/dt=100A/μs (note 4)	-	21	-	ns	
反向恢复电荷 Reverse recovery charge	Qrr		-	17	-	nC	

热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	80N75			单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	R _{th(j-c)}	0.65	0.65	1.42	°C/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	R _{th(j-A)}	62.5	62.5	105	°C/W

注释:

- 1: 脉冲宽度由最高结温限制
- 2: L=1mH, I_{AS}=10A, V_{DD}=48V, R_G=25 Ω, 起始结温 T_J=25°C
- 3: I_{SD} ≤ 80A, di/dt ≤ 300A/μs, V_{DD} ≤ BV_{DSS}, 起始结温 T_J=25°C
- 4: 脉冲测试: 脉冲宽度 ≤ 300μs, 占空比 ≤ 2%
- 5: 基本与工作温度无关

Notes:

- 1: Pulse width limited by maximum junction temperature
- 2: L=1mH, I_{AS}=10A, V_{DD}=48V, R_G=25 Ω, Starting T_J=25°C
- 3: I_{SD} ≤ 80A, di/dt ≤ 300A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J=25°C
- 4: Pulse Test: Pulse Width ≤ 300μs, Duty Cycle≤2%
- 5: Essentially independent of operating temperature

Typical Performance Characteristics

Fig 1: Output Characteristics

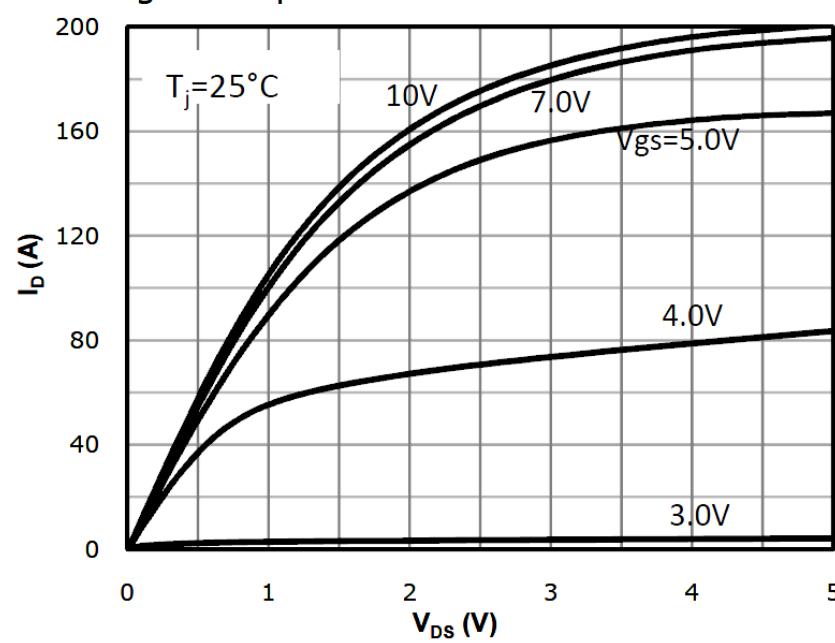


Fig 2: Transfer Characteristics

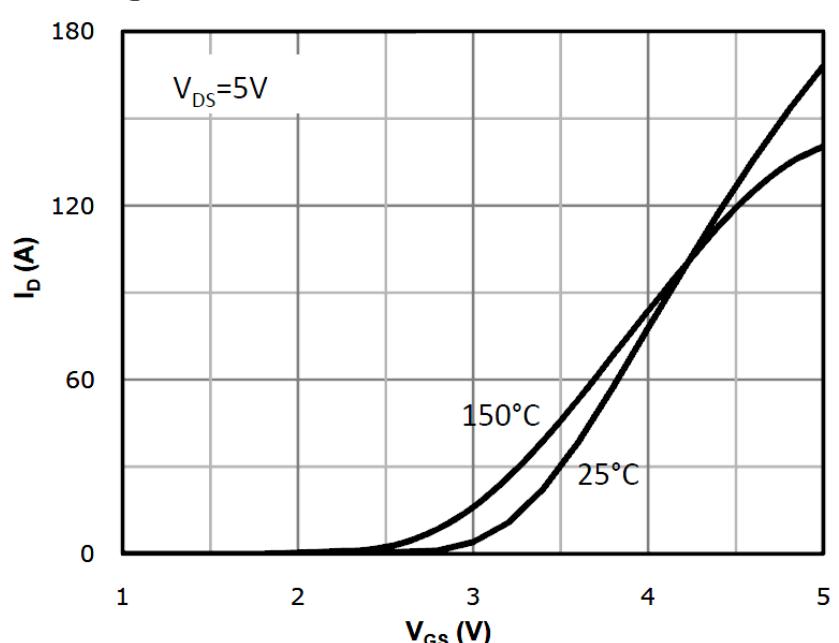


Fig 3: $R_{DS(on)}$ vs Drain Current and Gate Voltage

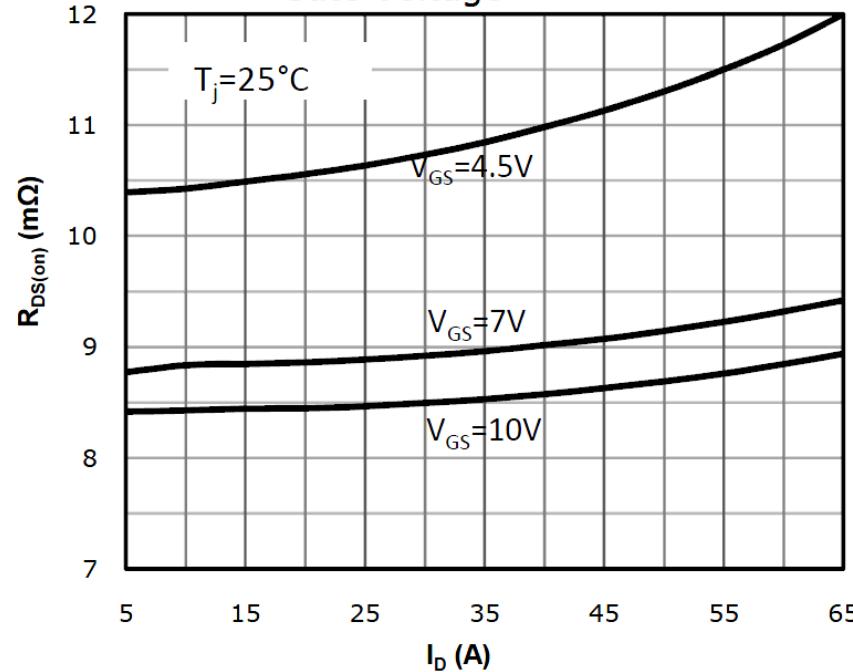


Fig 4: $R_{DS(on)}$ vs Gate Voltage

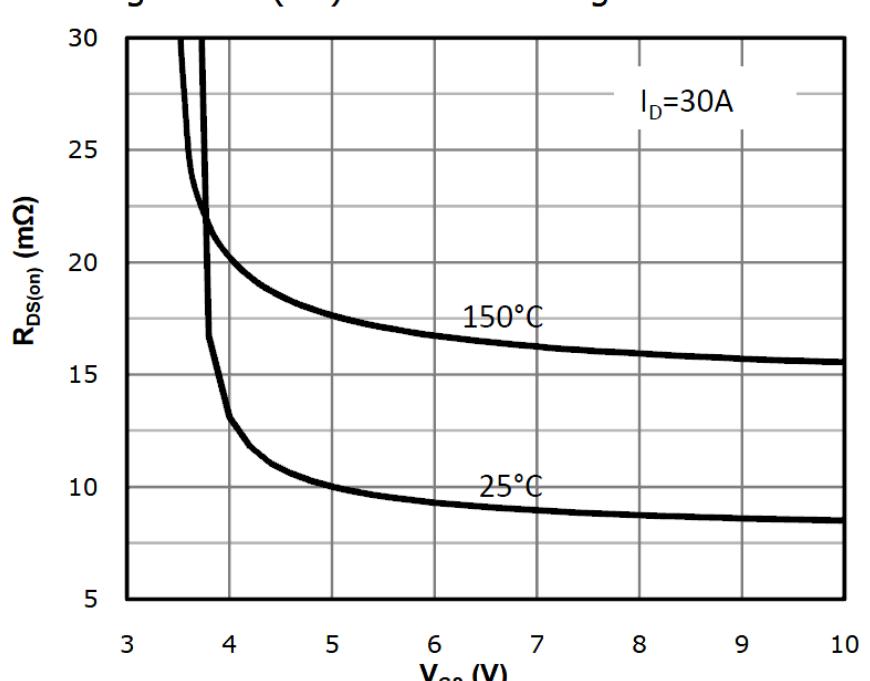


Fig 5: $R_{DS(on)}$ vs. Temperature

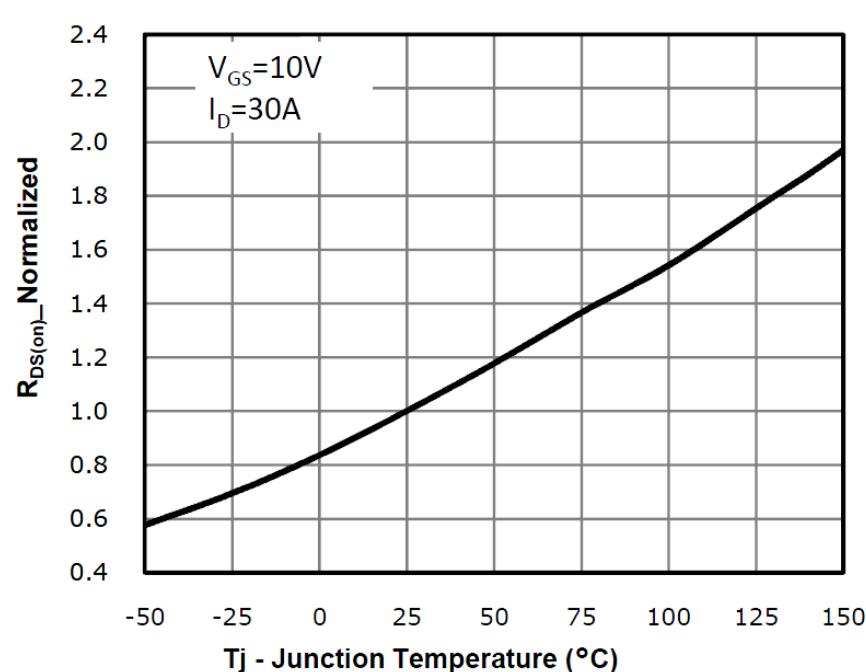


Fig 6: Capacitance Characteristics

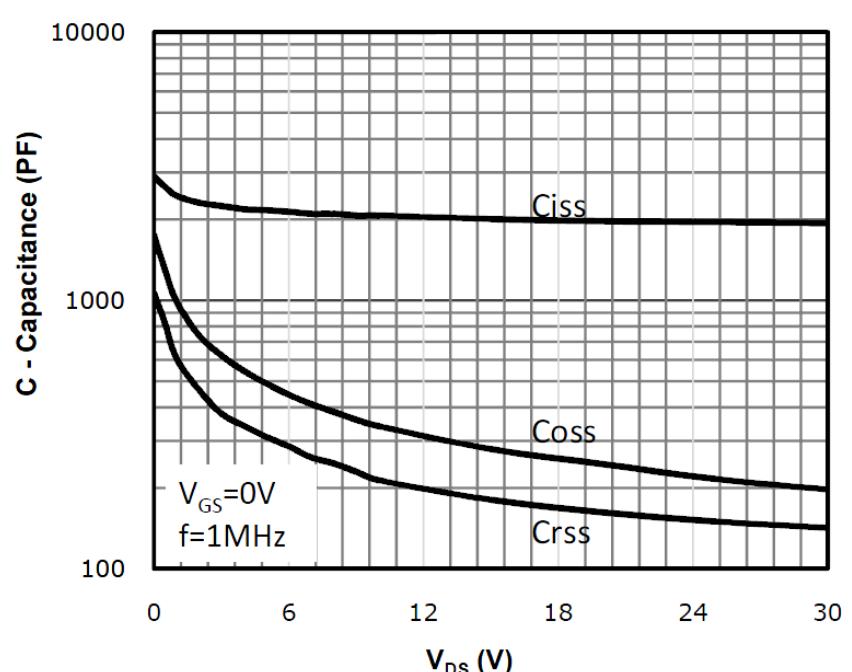


Fig 7: Gate Charge Characteristics

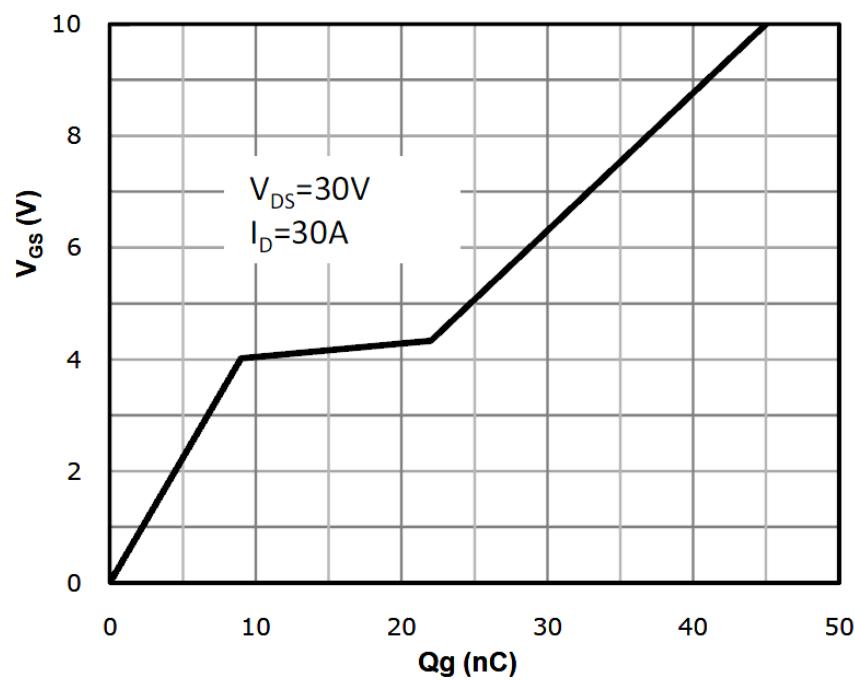


Fig 8: Body-diode Forward Characteristics

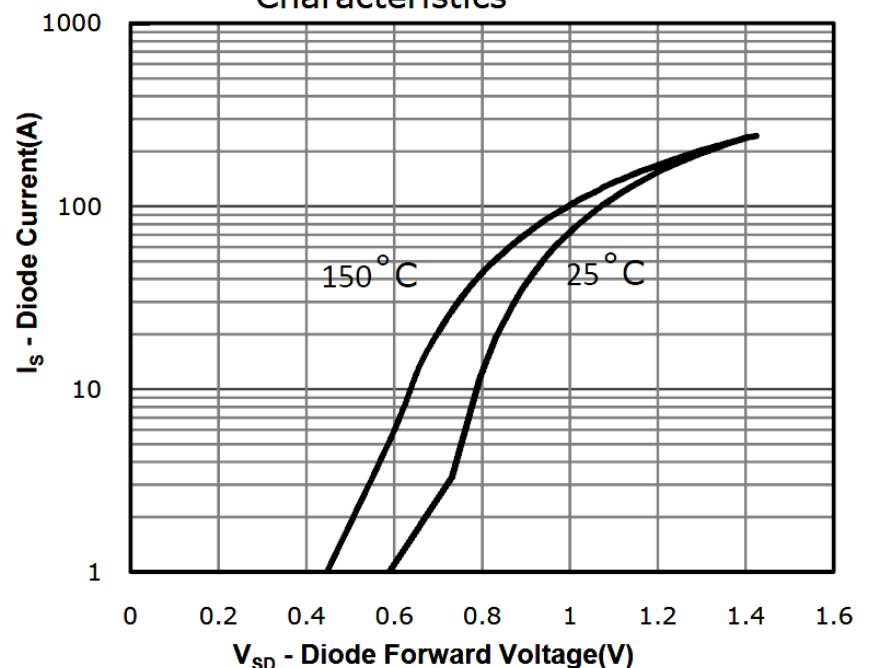


Fig 9: Power Dissipation

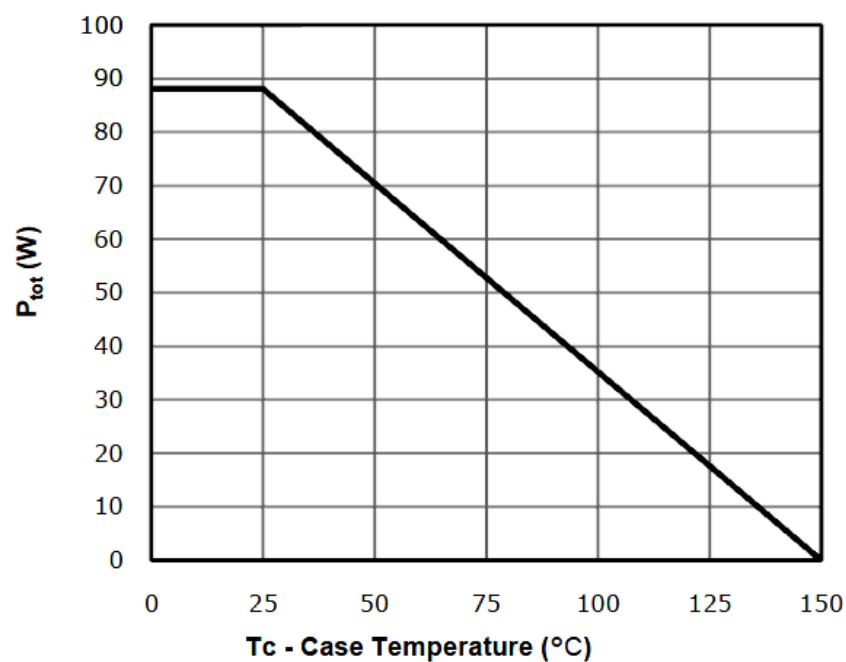


Fig 10: Drain Current Derating

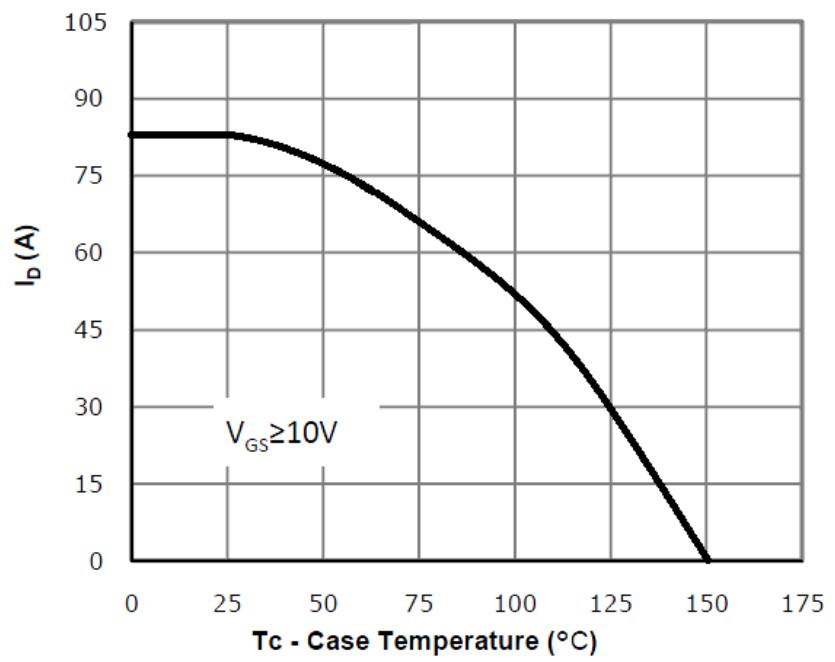


Fig 11: Safe Operating Area

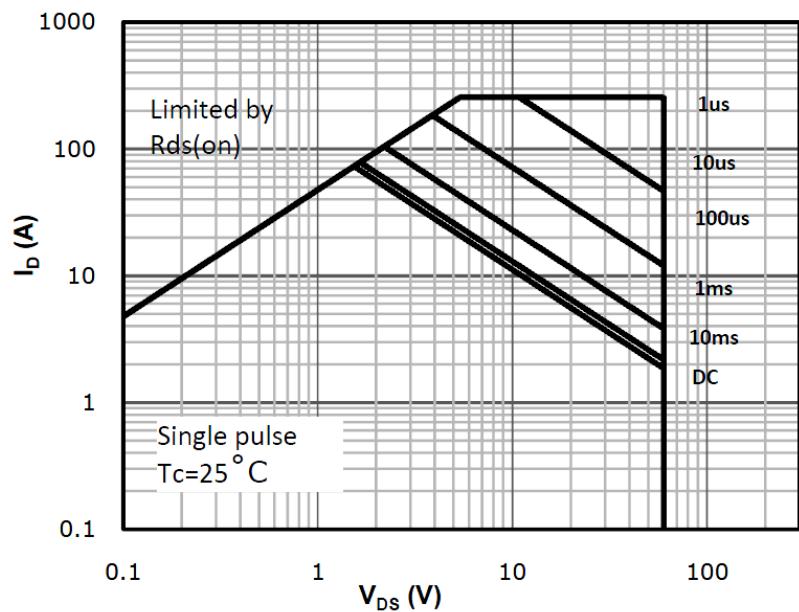
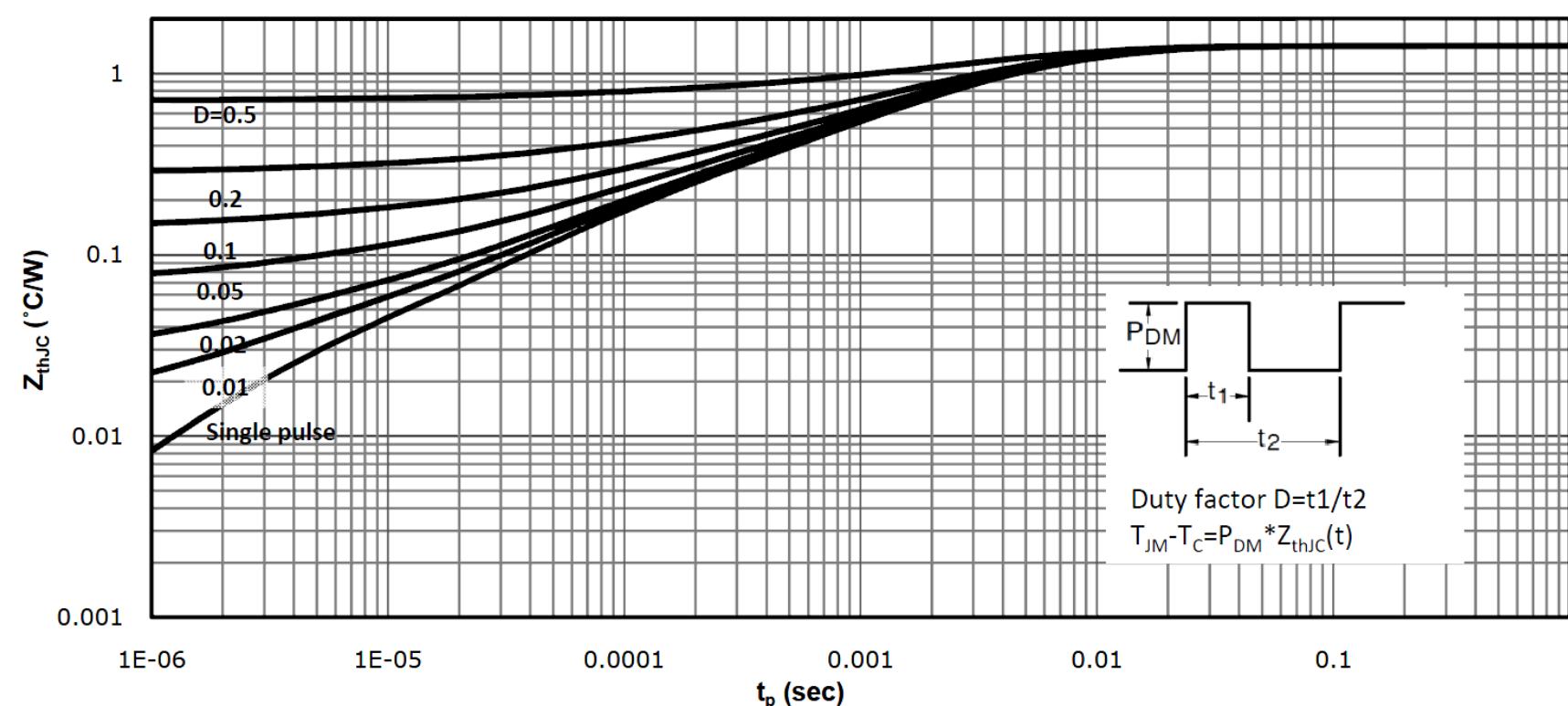
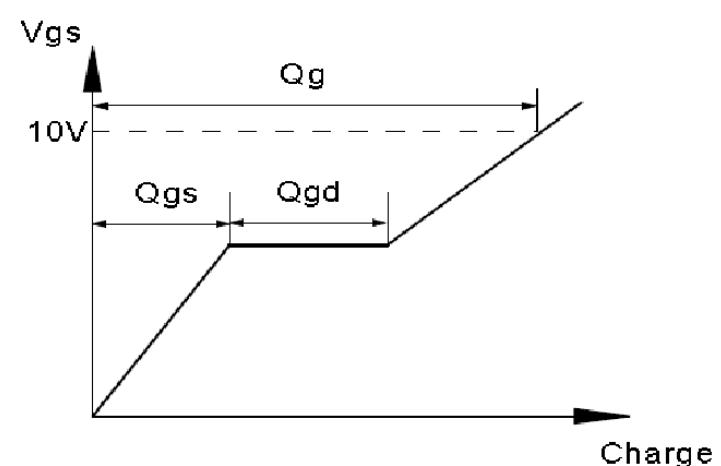
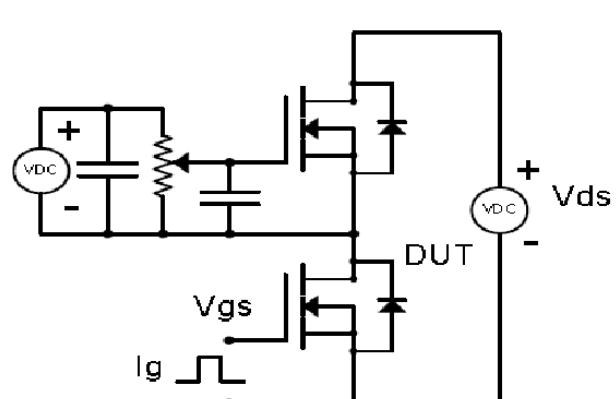


Fig 12: Max. Transient Thermal Impedance



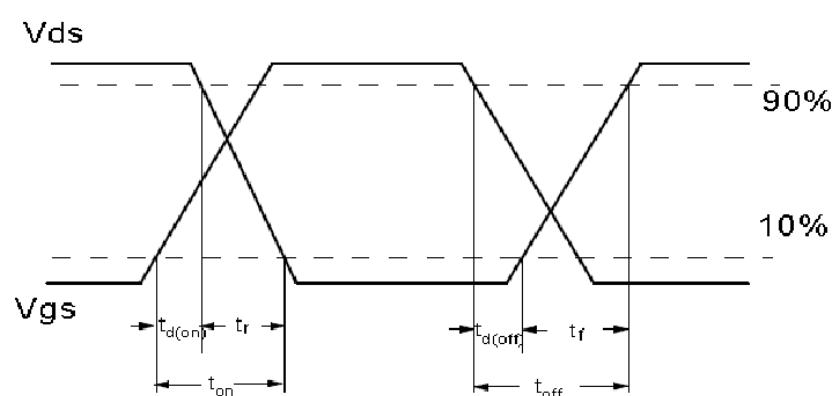
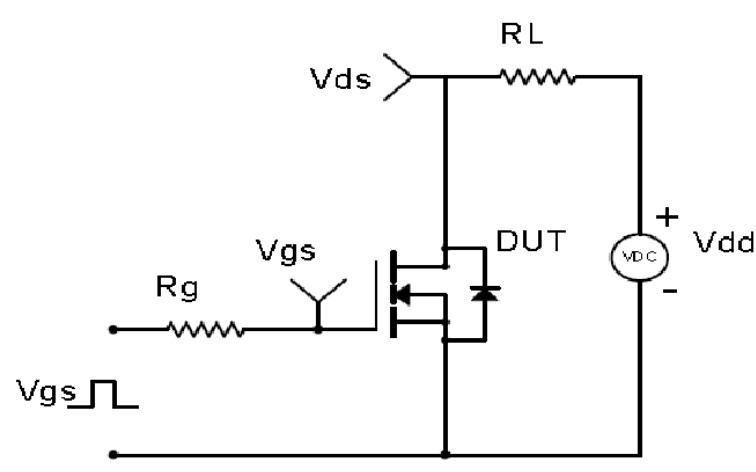
Test Circuit & Waveform

Gate Charge Test Circuit & Waveform

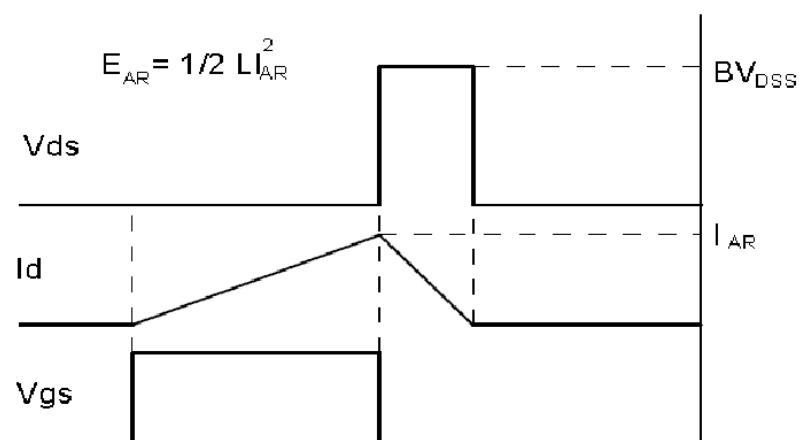
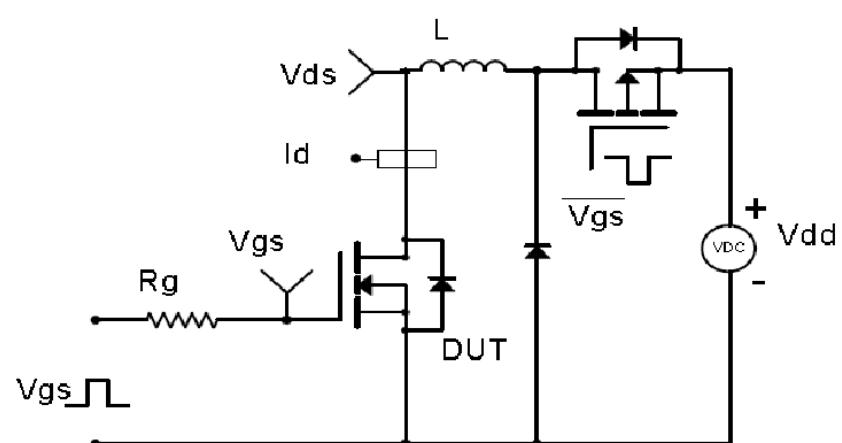


Resistive Switching Test Circuit & Waveforms

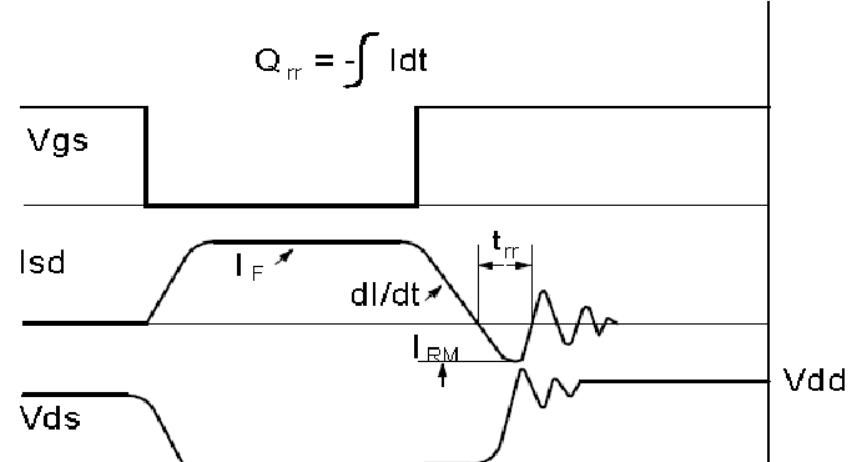
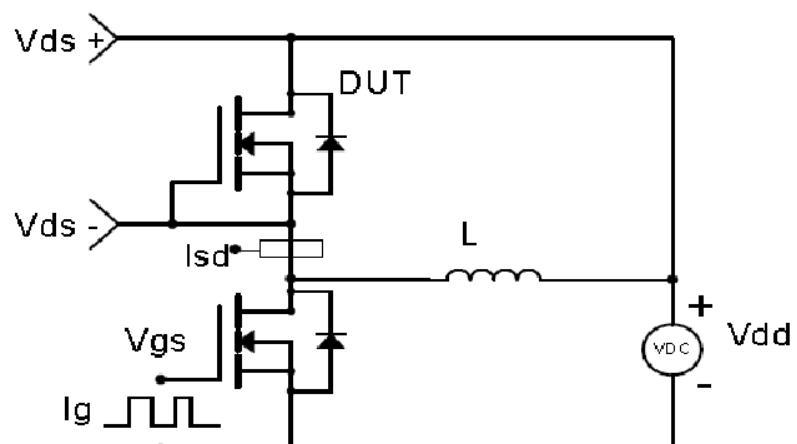
Resistive Switching Test Circuit & Waveforms



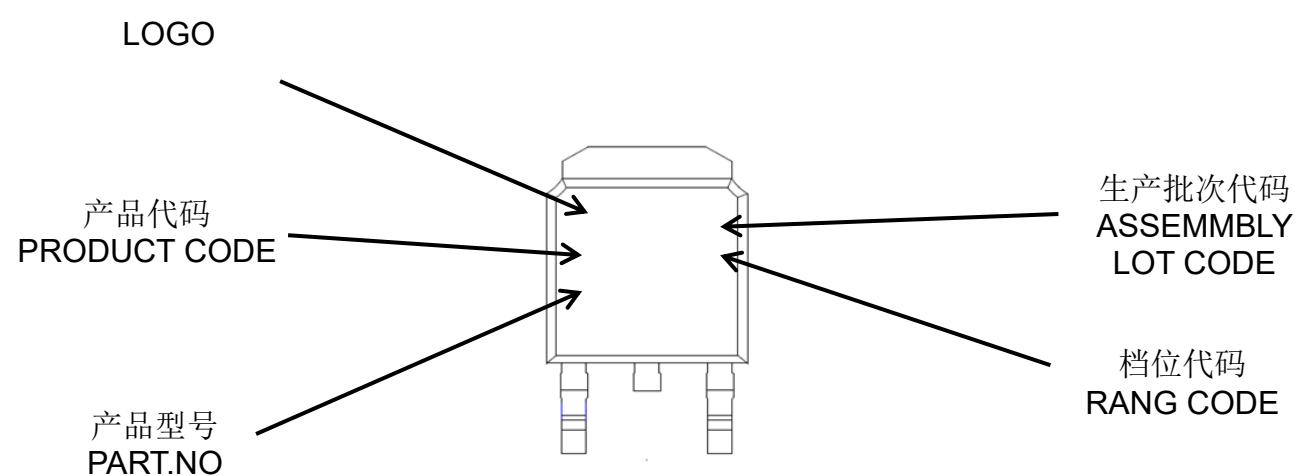
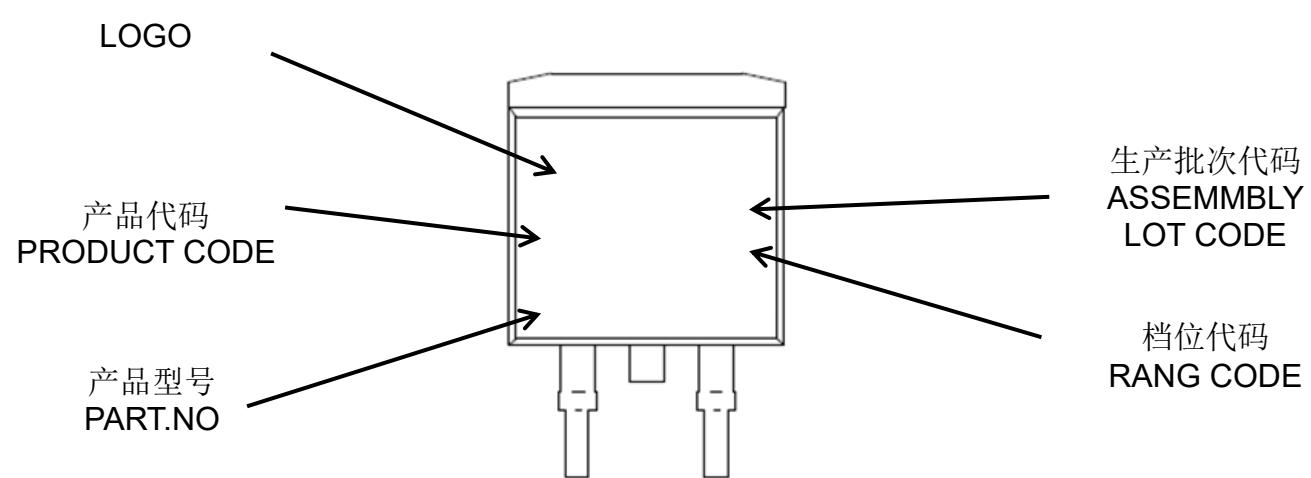
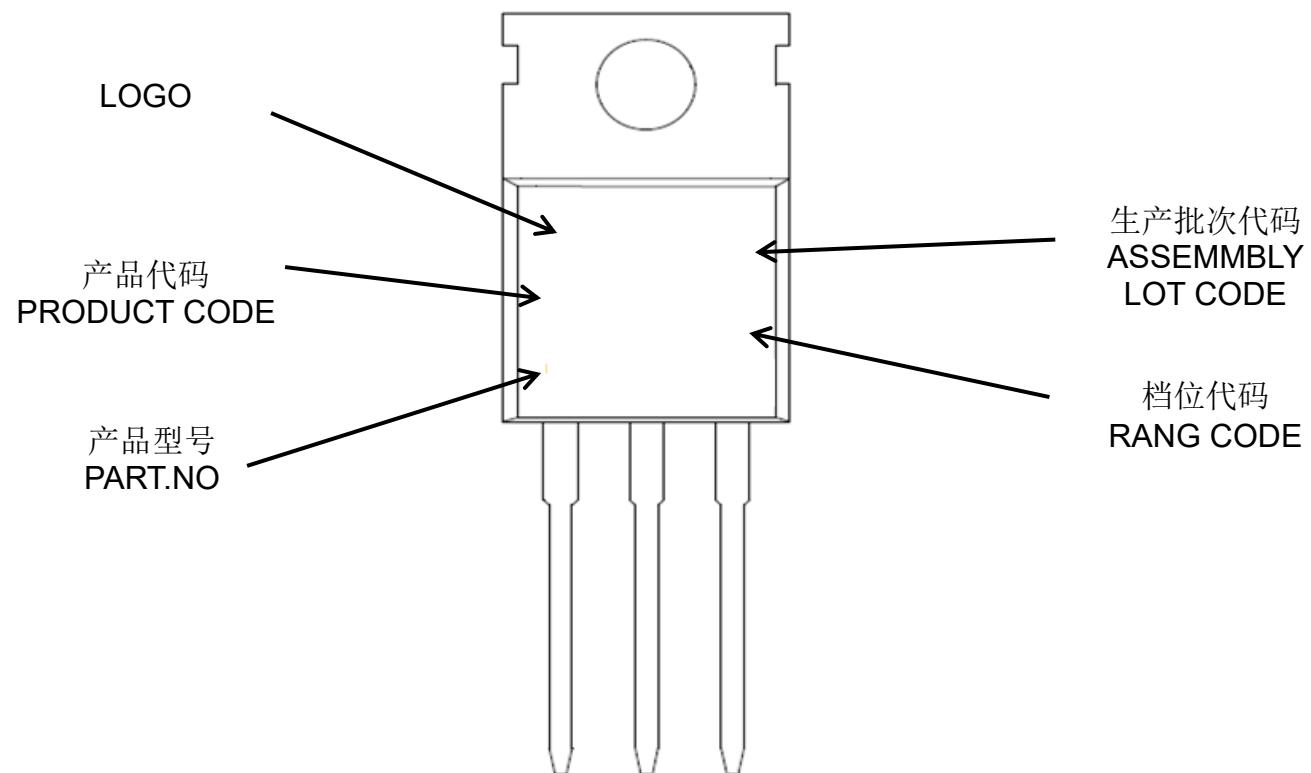
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



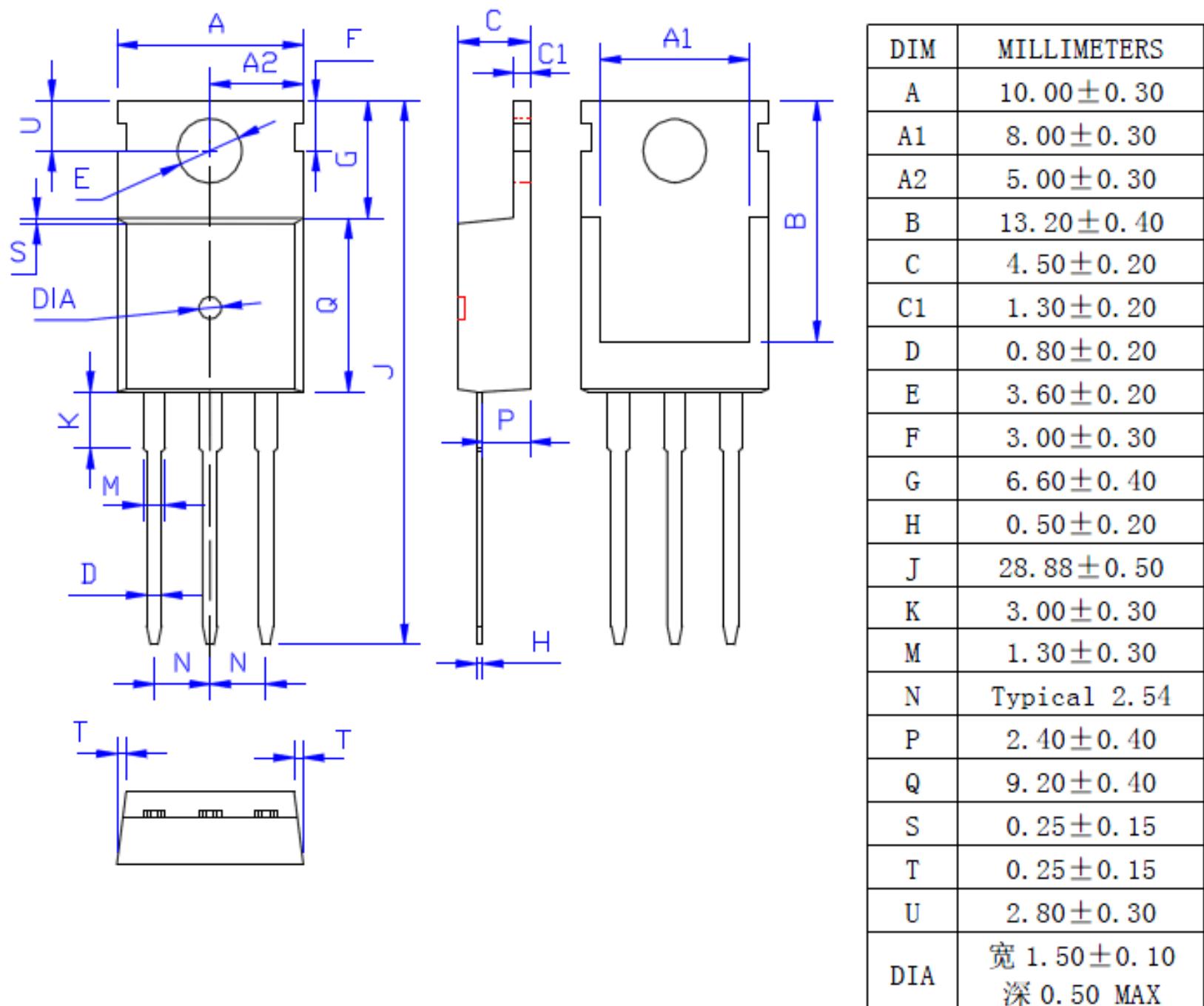
印记 Marking:



外形尺寸:

Package Dimension:

TO-220

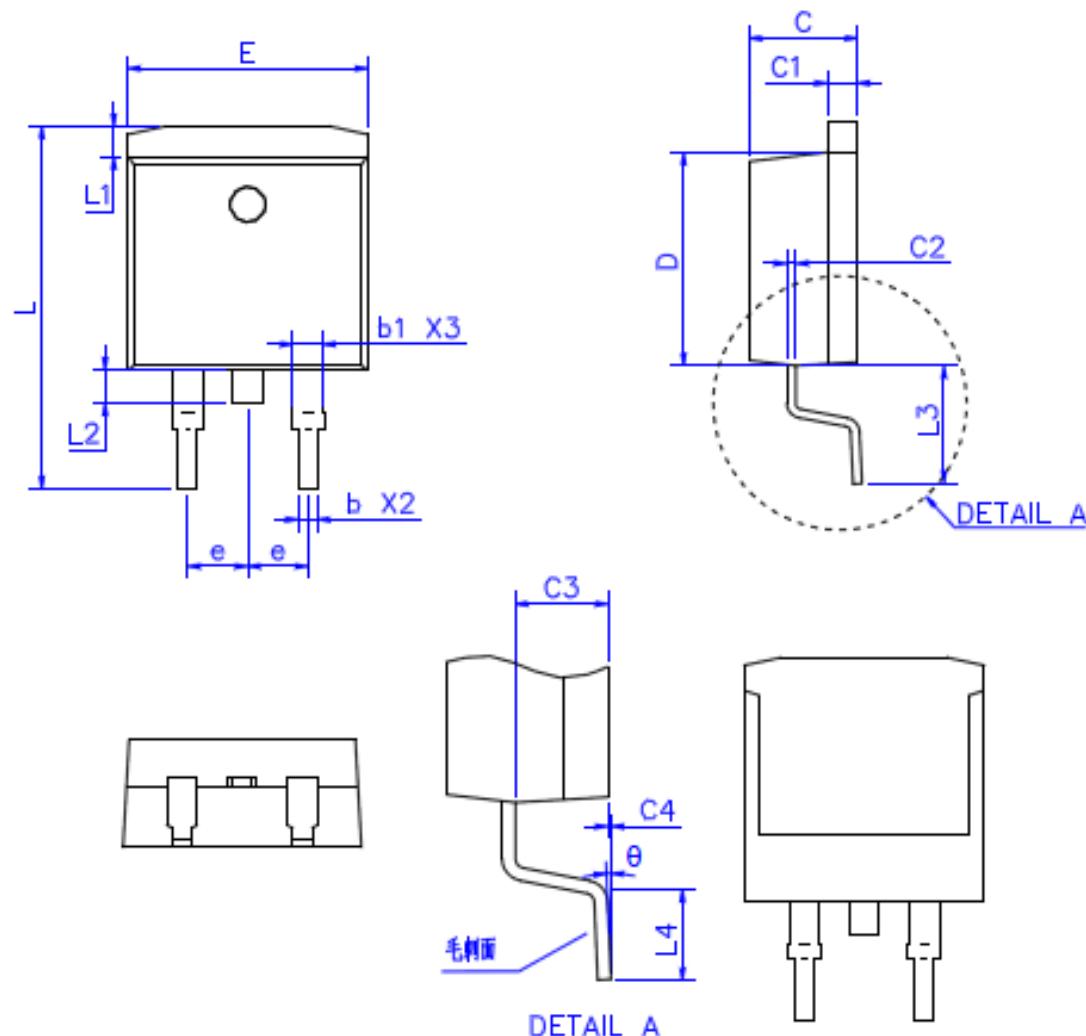


(Unit: mm)

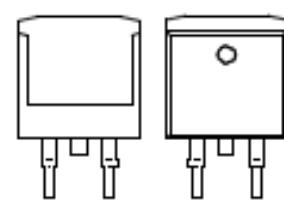
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Package Dimension:

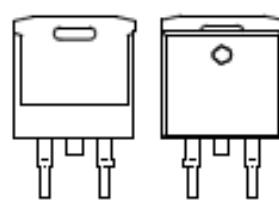
TO-263



DIM	MILLIMETERS	
	MIN	MAX
E	9.80	10.50
L	14.60	15.80
L1	1.00	1.55
L2	1.30	1.70
L3	4.50	5.50
L4	2.10	2.90
b	0.60	0.99
b1	1.00	1.50
C	4.30	4.80
C1	1.10	1.45
C2	0.25	0.52
C3	2.40	2.80
C4	0	0.25
D	8.50	9.50
θ	0°	8°
e	Typical	2.54



框架不带锁料孔



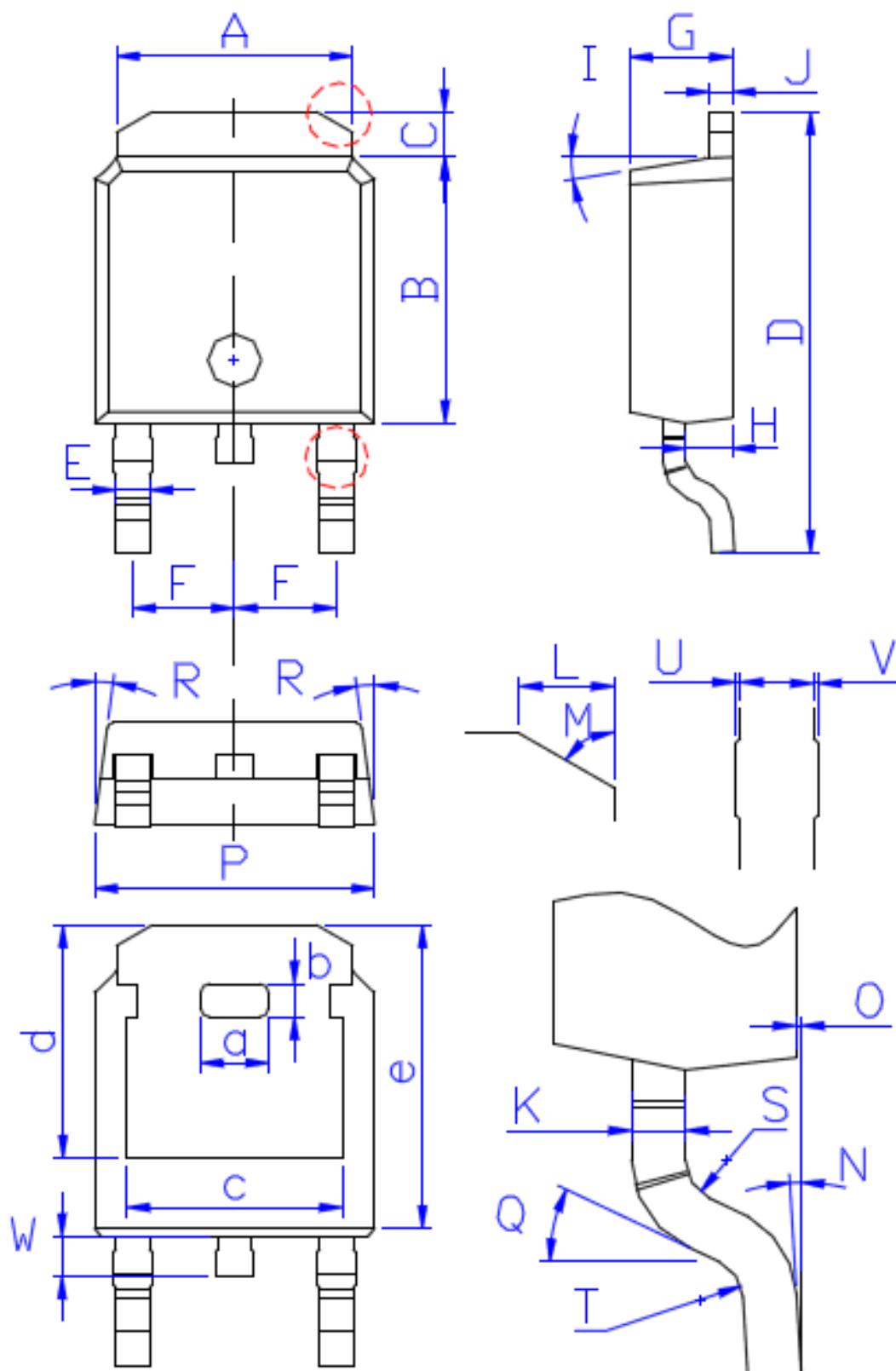
框架带锁料孔

(Unit: mm)

外形尺寸:

Package Dimension:

TO-252



DIM	MILLIMETERS
A	5.34±0.30
B	6.00±0.30
C	1.05±0.30
D	9.95±0.30
E	0.76±0.15
F	2.28±0.15
G	2.30±0.30
H	1.06±0.30
I	(4-10)°
J	0.51±0.15
K	0.52±0.15
L	0.80±0.30
M	60°
N	(0-10)°
O	0.05±0.05
P	6.60±0.30
Q	25°
R	(4-8.5)°
S	R0.40
T	R0.40
U	0.05±0.05
V	0.05±0.05
W	0.90±0.30
a	1.80±0.30
b	0.75±0.30
c	4.85±0.30
d	5.30±0.30
e	6.90±0.30

(Units: mm)